

**ABSTRACT OF THE DISCLOSURE**

A method of producing individual integrated circuit package units includes the steps of: providing a base which includes a leadframe, a plurality of package precursors, and a continuous encapsulating epoxy layer bonded integrally with the leadframe; and singulating the package precursors. The leadframe has a plurality of metallic connection bars and extension parts formed integrally with the connection bars. The package precursors are singulated by cutting the leadframe and the epoxy layer along first and second cutting streets. The cutting of the base is performed by cutting into the first and second cutting streets with a cutting tool, which can be a single-blade or dual-blade, thereby separating the connection bars from the inner leads.